



MP8840

8-Channel, Voltage Output,
2 MHz, 4 Quadrant
Multiplying, 8-Bit DAC with
Serial Digital Data Port

FEATURES

- 8 Independent 4-Quadrant Multiplying 8-Bit DACs
- High Speed:
 - Settling Time: 3.5 μ s to ± 1 LSB
 - Slew Rate: 4 V/ μ s
 - Voltage Reference Input Bandwidth: 2.5 MHz ($V_{IN} = 100$ mV p-p)
- Low Power: 80 mW (typ)
- DACs Matched to $\pm 0.5\%$ (typ)
- Midscale Preset, All DAC Outputs are Zero Volts
- Latch-Up Free
- Greater than 2000 V ESD Protection
- 5 MHz Version: MP7670

APPLICATIONS

- Analog Multiplier Replacement
- High-Frequency Gain Control using DACs
- Convergence Adjustment for Displays and Monitors
- Potentiometer Adjustment Replacement

GENERAL DESCRIPTION

The MP8840 is an 8-channel, 4 quadrant multiplying, 8-bit accurate digital-to-analog converter with a 2.5 MHz input bandwidth. It includes an output drive amplifier per channel capable of driving a ± 5 mA minimum to a load. DNL of $\pm 1/4$ LSB (typ) is achieved with a channel-to-channel matching of better than 0.5% (typ). Stability, matching, and precision of the DACs are achieved by using EXAR's thin film technology.

The MP8840 is ideal for direct gain control of high frequency analog signals. The bipolar output amplifier has low noise which

produces a very sharp signal output particularly in display and monitor applications.

A proprietary subranging architecture provides wide signal bandwidth from V_{IN} to output up to 2.5 MHz (typ), fast output settling time, and V_{IN} feedthrough isolation of -60 dB (typ).

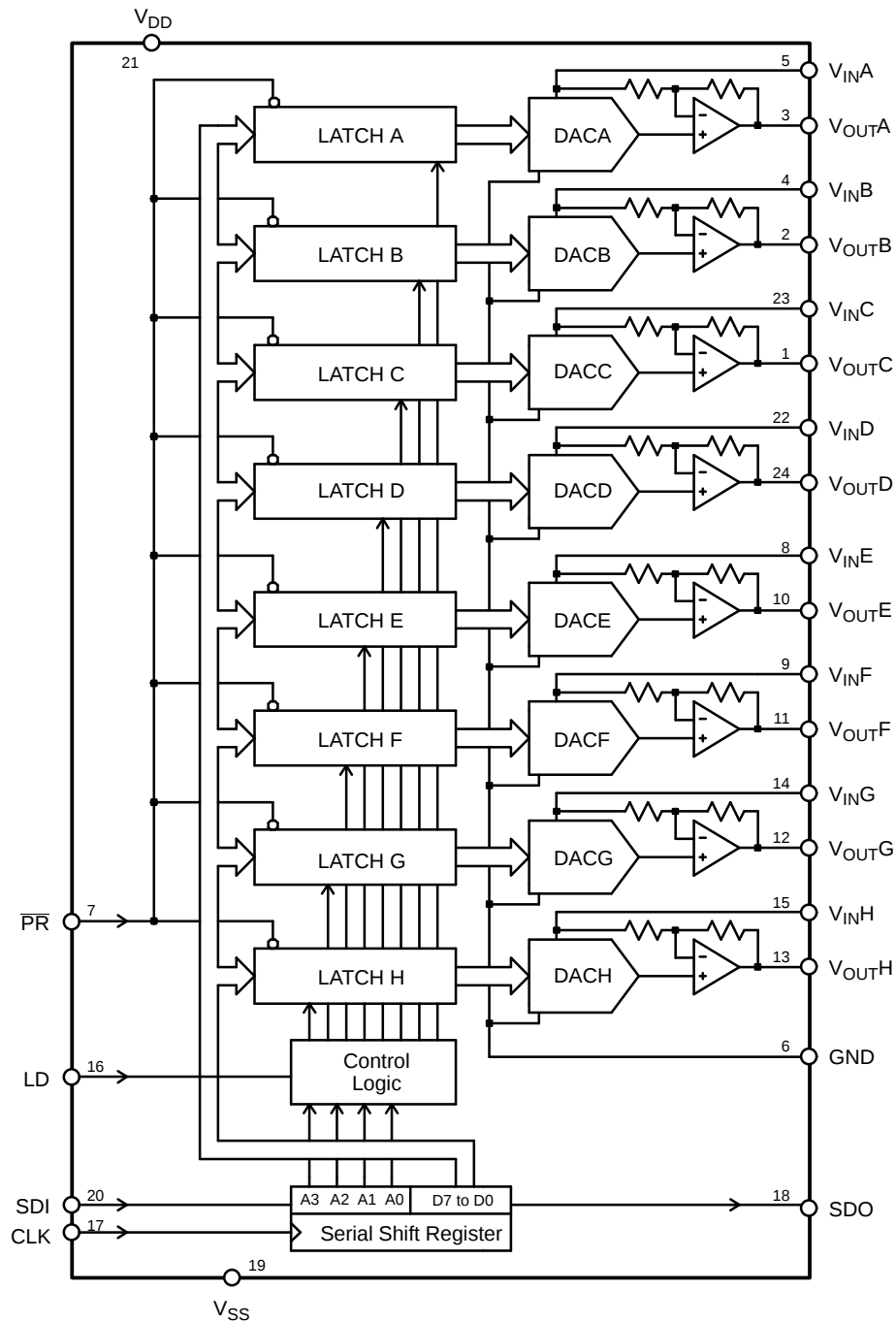
The MP8840 has a serial data 3-wire standard μ -processor logic interface to reduce pin count, package size, and board wire (space).

The MP8840 is fabricated on a junction isolated, high speed BiCMOS1TM process with thin film resistors.

ORDERING INFORMATION

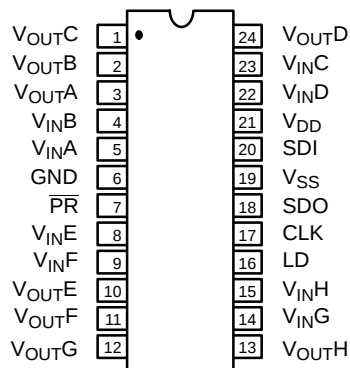
Package Type	Temperature Range	Part No.
Plastic Dip	-40 to $+85^{\circ}\text{C}$	MP8840AN
SOIC	-40 to $+85^{\circ}\text{C}$	MP8840AS

SIMPLIFIED BLOCK DIAGRAM

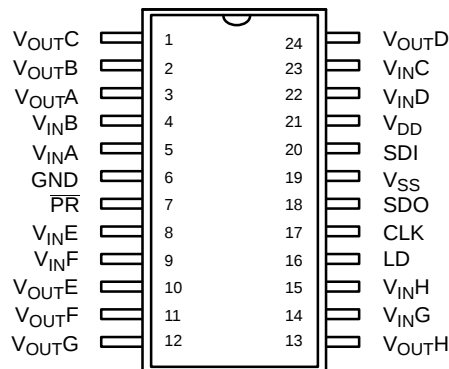


PIN CONFIGURATIONS

See Packaging Section for
Package Dimensions



**24 Pin PDIP (0.300")
NN24**



**24 Pin SOIC (Jedec, 0.300")
S24**

PIN OUT DEFINITIONS

PIN NO.	NAME	DESCRIPTION
1	V _{OUTC}	DAC C Output
2	V _{OUTB}	DAC B Output
3	V _{OUTA}	DAC A Output
4	V _{INB}	DAC B Reference Input
5	V _{INA}	DAC A Reference Input
6	GND	Ground
7	$\overline{\text{PR}}$	Preset Input, Active Low
8	V _{INE}	DAC E Reference Input
9	V _{INF}	DAC F Reference Input
10	V _{OUTE}	DAC E Output
11	V _{OUTF}	DAC F Output
12	V _{OUTG}	DAC G Output

PIN NO.	NAME	DESCRIPTION
13	V _{OUTH}	DAC H Output
14	V _{ING}	DAC G Reference Input
15	V _{INH}	DAC H Reference Input
16	LD	Load DAC Register Strobe, Active High Input
17	CLK	Serial Clock Input
18	SDO	Serial Data Output
19	V _{SS}	Negative Power Supply
20	SDI	Serial Data Input
21	V _{DD}	Positive Power Supply
22	V _{IND}	DAC D Reference Input
23	V _{INC}	DAC C Reference Input
24	V _{OUTD}	DAC D Output

ELECTRICAL CHARACTERISTICS TABLE FOR DUAL SUPPLIES

Unless Otherwise Noted: $V_{DD} = 5\text{ V}$, $V_{SS} = -5\text{ V}$, $GND = 0\text{ V}$, $V_{INX} = 3\text{ V}$

Parameter	Symbol	25°C			Tmin to Tmax		Units	Test Conditions/Comments
		Min	Typ	Max	Min	Max		
DC CHARACTERISTICS								
Resolution (All Grades)	N	8			8		Bits	
Differential Non-Linearity	DNL		±1/4	±1		±1	LSB	
Integral Non-Linearity	INL			±1		±1	LSB	
Monotonicity		Guaranteed						
DAC OUTPUT								
Output Offset	V _{BZE}		3	25			mV	PR¯ = 0, Sets Code = 80 _H
Voltage Range	OVR	−3		3	−3	3	V	
Output Current	I _{OUT}	±5	±10		±5		mA	ΔV _{OUT} <1 LSB
Capacitive Load	CL			200		200	pF	No oscillations
REFERENCE INPUTS								
Input Resistance of one DAC	R _{IN}	5			5		KΩ	R _{IN} (typ) = 15KΩ//R _x R _x = 20KΩ/(1-Code/256)
Input Capacitance ²	C _{IN}		19	30			pF	
Voltage Range ¹	IVR	−3		3	−3	3	V	
DYNAMIC CHARACTERISTICS ²								
Input to Output Bandwidth	BW	1	2.5				MHz	Code = FS, V _{INX} = 100 mV p-p Measured 10% to 90%, ΔV _{OUTX} = ±6 V Code = HS, up to f = 100 kHz V _{INX} = 4 V p-p, Code = FS f = 1 kHz, f _{LP} = 80 kHz f = 1 kHz ±1 LSB, Code = 0 to FS Measured between adjacent channels, f = 100 kHz V _{INX} = 0 V, Code = 0 to FS
Slew Rate	SR	1.3	4.0				V/μs	
V _{IN} Feedthrough	F _{DT}		−60				dB	
Total Harmonic Distortion	T _{HD}		0.02				%	
Spot Noise Voltage	e _N		0.17				μV/√Hz	
Output Settling Time	t _S		3.5	6.0			μs	
Channel-to-Channel Crosstalk	C _T	60					dB	
Digital Feedthrough	Q		6				nVs	
DIGITAL INPUTS								
Logic High ³	V _{IH}	2.4			2.4		V	
Logic Low ³	V _{IL}			0.8		0.8	V	
Input Current	I _L			±1		±1	μA	
Input Capacitance ²	C _L			8		8	pF	
DIGITAL OUTPUTS								
Logic High	V _{OH}	3.5			3.5			I _{OH} = −0.4 mA
Logic Low	V _{OL}			0.4		0.4		I _{OL} = 1.6 mA
POWER SUPPLIES								
Power Supply Range	V _{DD}	4.5		5.5	4.5	5.5	V	PR¯ = 0 V, ΔV _{DD} = ±5% PR¯ = 0 V, ΔV _{SS} = ±5%
	V _{SS}	−5.5		−4.5	−5.5	−4.5	V	
Power Supply Rejection Ratio								
Positive	PSRR+		0.0002	0.01			%/%	
Negative	PSRR−		0.0002	0.01			%/%	

ELECTRICAL CHARACTERISTICS TABLE

Description	Symbol	25°C			Tmin to Tmax		Units	Conditions
		Min	Typ	Max	Min	Max		
POWER SUPPLIES (CONT'D)								
Power Dissipation	P _{DISS}		80	150			mW	$\overline{PR} = 0\text{ V}$
Power Supply Current	I _{DD}		8	15			mA	$\overline{PR} = 0\text{ V}$
Negative Supply Current	I _{SS}		8	15			mA	$\overline{PR} = 0\text{ V}$
DIGITAL TIMING SPECIFICATIONS ^{2, 4}								
Input Clock Pulse Width	t _{CH} , t _{CL}	80					ns	
Data Setup Time	t _{DS}	40					ns	
Data Hold Time	t _{DH}	20					ns	
CLK to SDO Propagation Delay	t _{PD}			120			ns	
Load Pulse Width	t _{LD}	70					ns	
Preset Pulse Width	t _{PR}	50					ns	
Clock Edge to Load	t _{CKLD}	30					ns	
Load Edge to Next Clk Edge	t _{LDCK}	60					ns	

NOTES

- Maximum input voltage is 2 V less than V_{DD} .
- Guaranteed but not production tested.
- Digital input levels should not go below ground or exceed the positive supply voltage, otherwise damage may occur.
- See timing diagram.

Specifications are subject to change without notice

ABSOLUTE MAXIMUM RATINGS ($T_A = +25^\circ\text{C}$ unless otherwise noted)^{1, 2}

V_{DD} to GND +6.5 V
 V_{SS} to GND -6.5 V
 V_{INA-H} to GND V_{DD} to V_{SS}
 V_{OUTA-H} to GND V_{DD} to V_{SS}
 Digital Input & Output Voltage to GND . -0.5 to V_{DD} +0.5 V
 Operating Temperature Range
 Extended Industrial -40°C to +85°C

Maximum Junction Temperature -65°C to +150°C
 Storage Temperature 150°C
 Lead Temperature (Soldering 10 seconds) +300°C
 Package Power Dissipation Rating @ 75°C
 PDIP, SOIC 1000mW
 Derates above 75°C 14mW/°C

NOTES:

- Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.
- Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082-2835) from input pin to the supplies. *All inputs have protection diodes* which will protect the device from short transients outside the supplies of less than 100mA for less than 100μs.

THEORY OF OPERATION

The MP8840 contains 8 independent 4-quadrant multiplying D/A converters with output amplifiers. The design has incorporated a novel approach that provides fast, accurate, low noise, low distortion, small size, and low power in the same device. This device is particularly useful in applications where multipliers are used to perform the gain adjustment function for high frequency analog signal conditioning. Also note that typical multipliers tend to increase noise particularly for low gain settings and have high offsets. The MP8840 design delivers a very low, constant noise, and low offset with digital control through the entire gain range of the D/A converter.

Linearity Characteristics

Each D/A converter in the MP8840 achieves $DNL \leq \pm 0.25$ LSB (typ), and gain error $\leq \pm 0.5\%$ (typ). Since all 8 channels of MP8840 are fabricated in the same IC, the linearity, gain, and input-output characteristics of all 8 channels match extremely well.

The Logic Interface and Serial Port

The MP8840 is equipped with a serial data 3-wire standard μ -processor logic interface to reduce pin count, package size, and board wire. This interface consists of LD which controls the transfer of data to the selected DAC channels that are fed

through the SDI (serial digital data and address bits) with the CLK (digital input shift register clock). Please refer to the following timing diagrams and truth tables for logic details.

A SDO (serial digital data output driver) is connected to the other side of the input shift register and would save SDI bus space by allowing the daisy chaining of several MP8840s (connecting SDI of device 2 to SDO of device 1).

When the LD signal is low, CLK signal loads the digital input bits (SDI) into the 12-bit shift register. The LD signal going high loads this data into the selected DACs. Also, when the $\overline{PR}$ signal is low, the output of all DACs would be reset to 0 volts.

Power Supplies and Input Voltage Ranges

The output and input DC ranges are limited to within ± 2 V from each positive and negative supplies. For example, with supplies at ± 5 V, the recommended output range is ± 3 V.

The MP8840 design eliminates any code dependent current change into its GND, hence easing the board level design by eliminating the stringent need for other types of DACs for low GND impedance wiring considerations at board level.

Each output of the MP8840 DAC has an output amplifier driver delivering less than 0.05Ω of output impedance through a push-pull linear output stage. Each output and input characteristics parameter match extremely well, given that all channels are fabricated in the same IC.

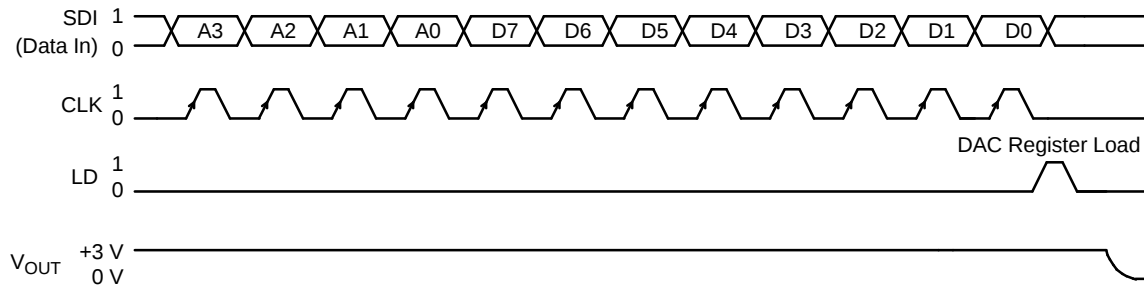


Figure 1. Serial Data Timing and Loading

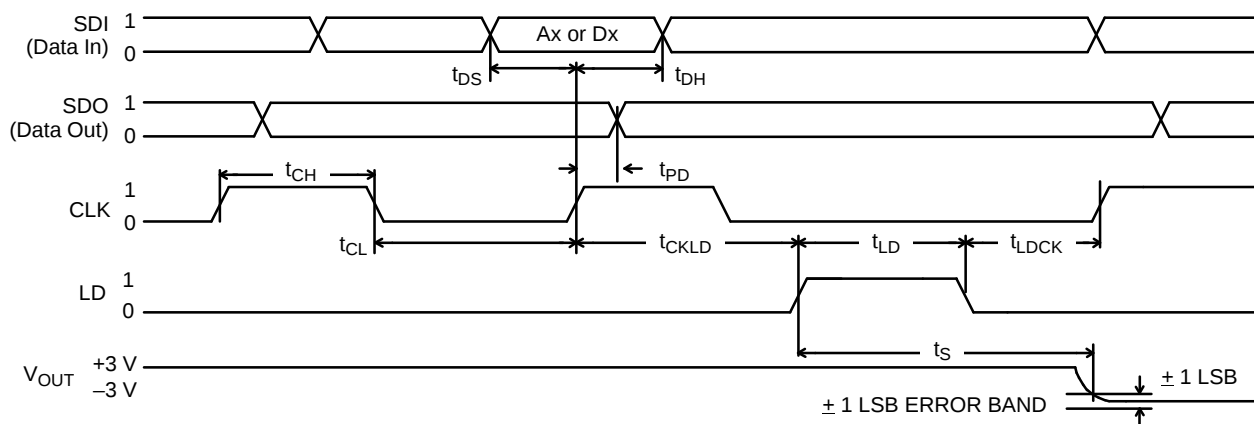


Figure 2. Detail Serial Data Input Timing ($\overline{PR} = "1"$)

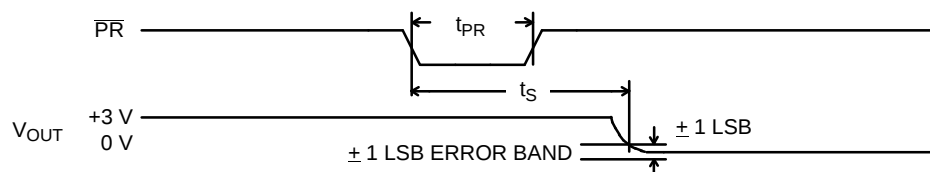


Figure 3. PRESET Operation

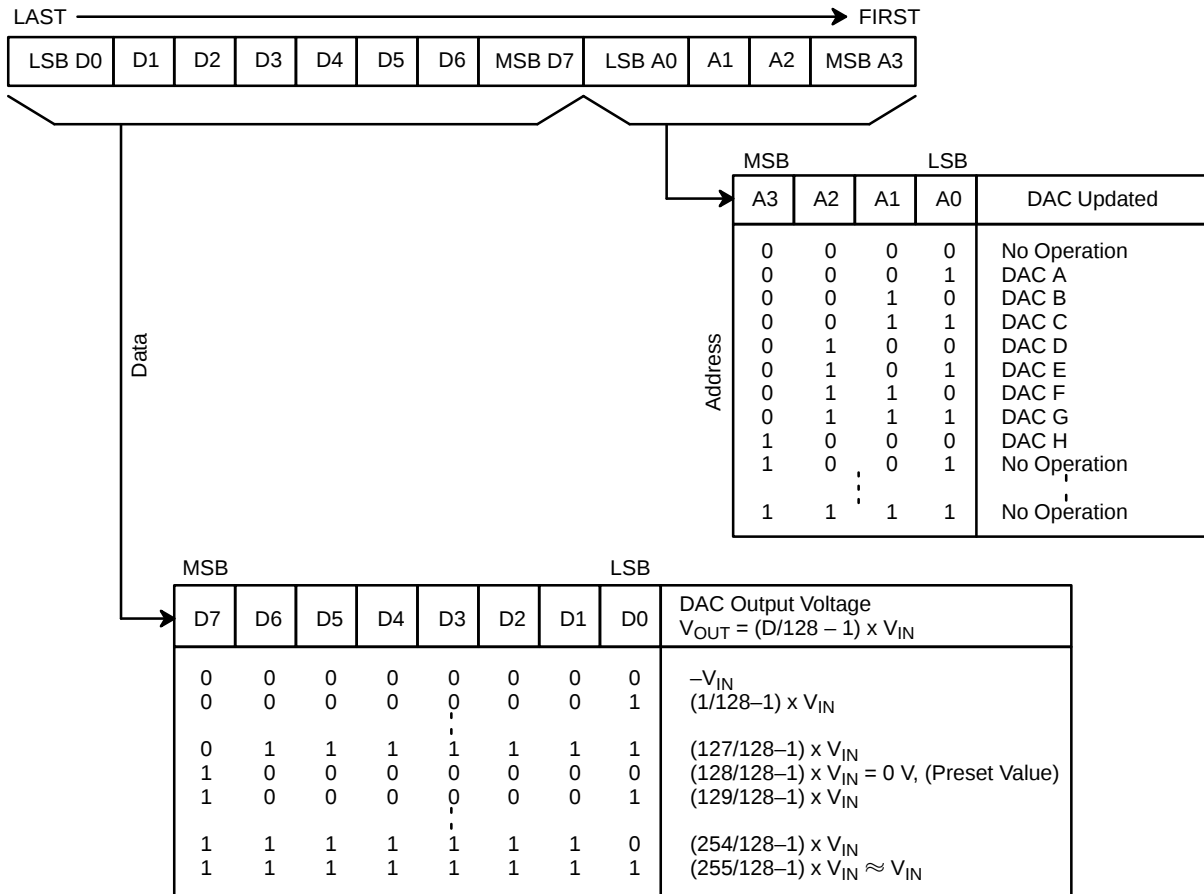


Table 1. Serial Input Format

SDI	CLK	LD	$\overline{\text{PR}}$	Input Shift Register Operation
X	L	L	H	No Operation
X	$\uparrow$	L	H	Shift One Bit In from SDI (Pin 20), Shift One Bit* Out from SDO (Pin 18)
X	X	L	L	All DAC Registers = 80 _H
X	L	H	H	Load Serial Register Data into DAC(X) Register

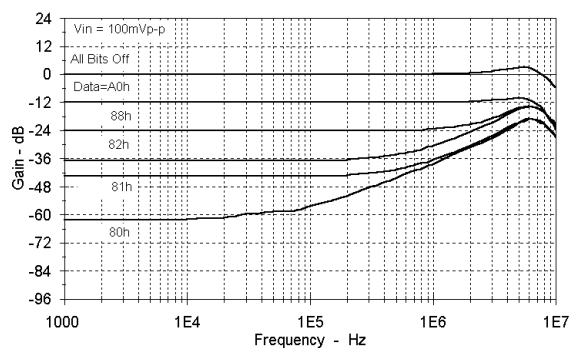
*Data shifted into the SDI pin appears twelve clocks later at the SDO pin.

Table 2. Control Logic Truth Table

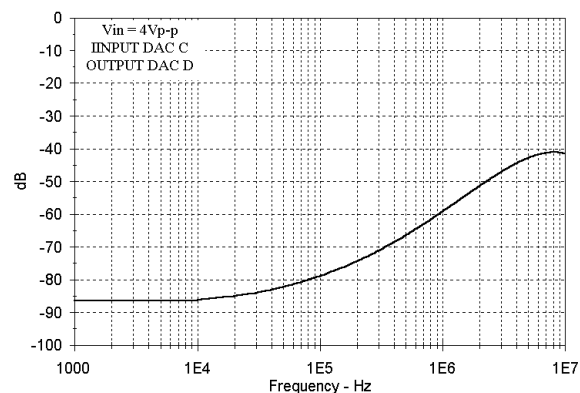
Decimal Input (D)	V_{OUT} (D)	Comments ($V_{IN} = 3 \text{ V}$)
0	-3.00 V	Inverted FS
1	-2.98	
127	-0.02	
128	0.00	Zero Output
129	0.02	
254	2.95	
255	2.98	Full Scale (FS)

Table 3. DAC Transfer Function

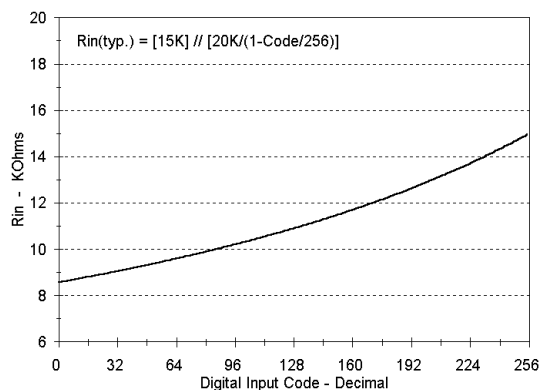
PERFORMANCE CHARACTERISTICS



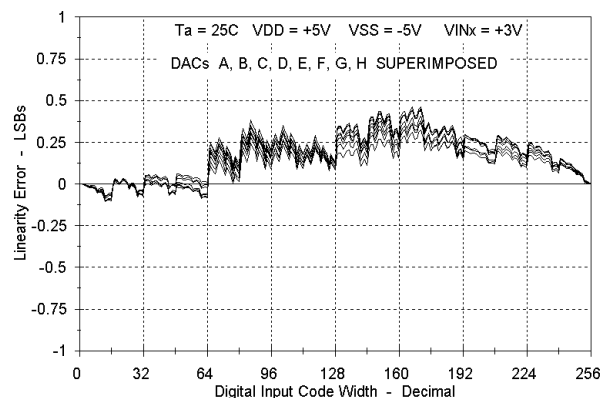
Graph 1. Gain (V_{OUT}/V_{IN}) and Feedthrough vs. Frequency



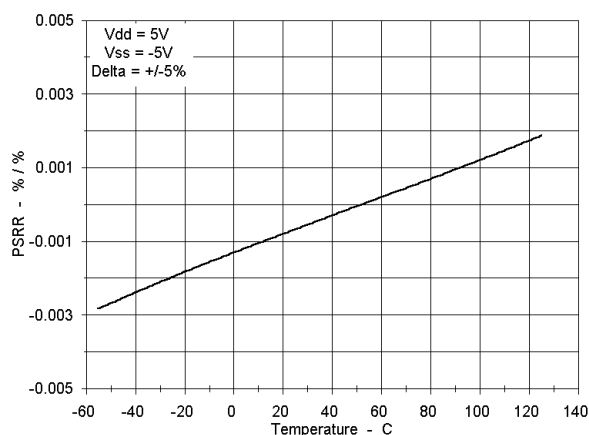
Graph 2. DAC Crosstalk vs. Frequency



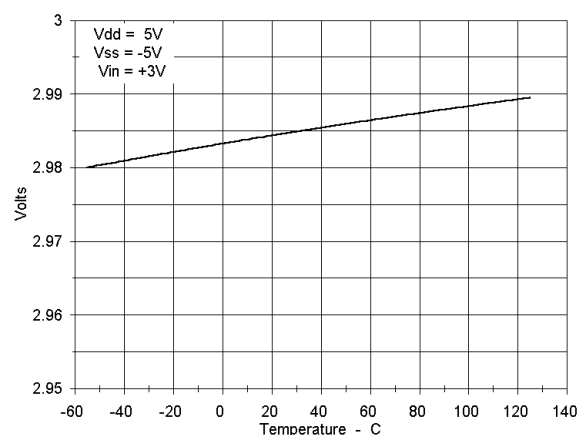
Graph 3. DAC Input Resistance vs. Digital Input Code



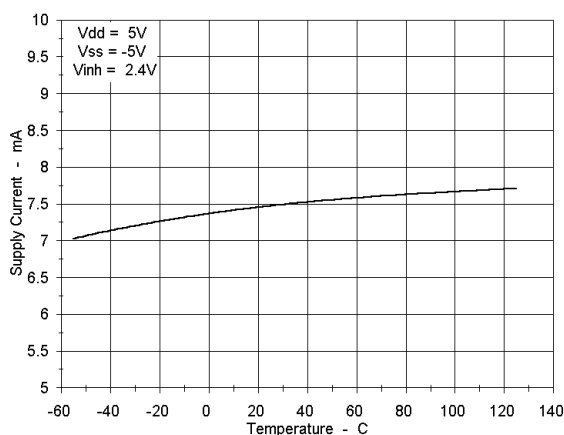
Graph 4. Linearity Error vs. Digital Input Code



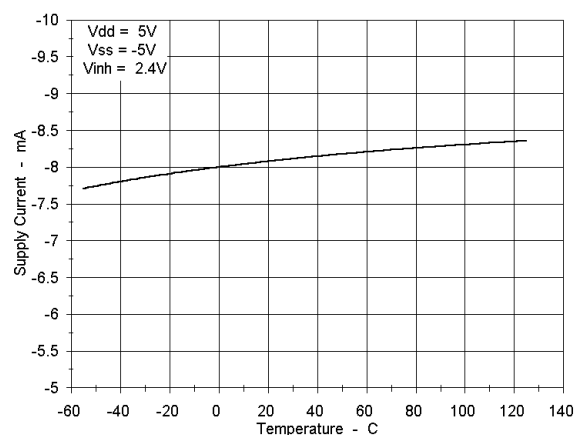
Graph 5. PSRR (DC) vs. Temperature



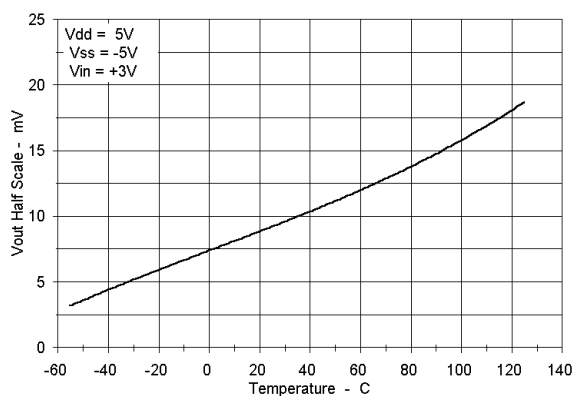
Graph 6. V_{OUT} Full Scale vs. Temperature



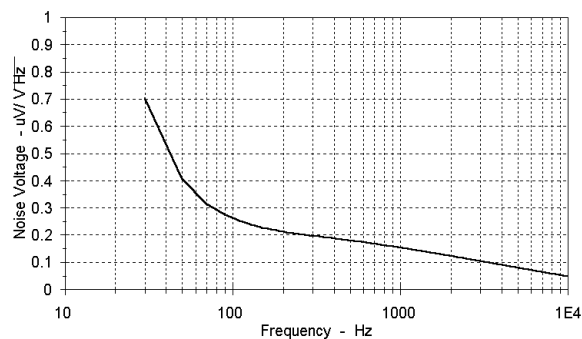
Graph 7. Supply Current (I_{DD}) vs. Temperature



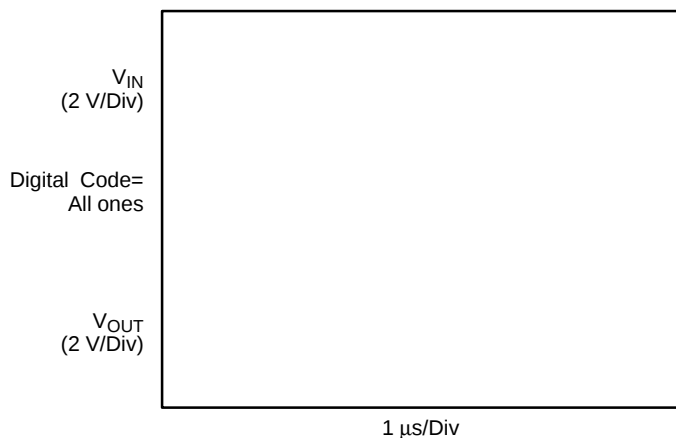
Graph 8. Supply Current (I_{SS}) vs. Temperature



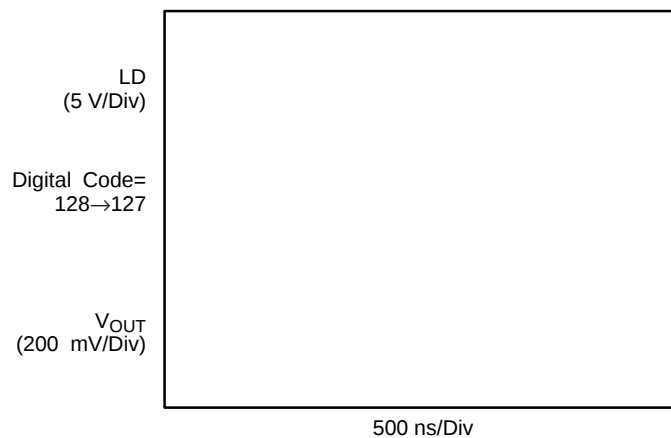
Graph 9. V_{OUT} Offset Error vs. Temperature



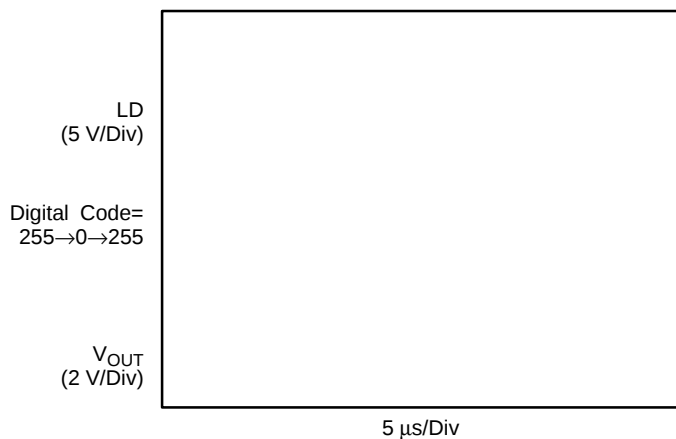
Graph 10. Voltage Noise Density vs. Frequency



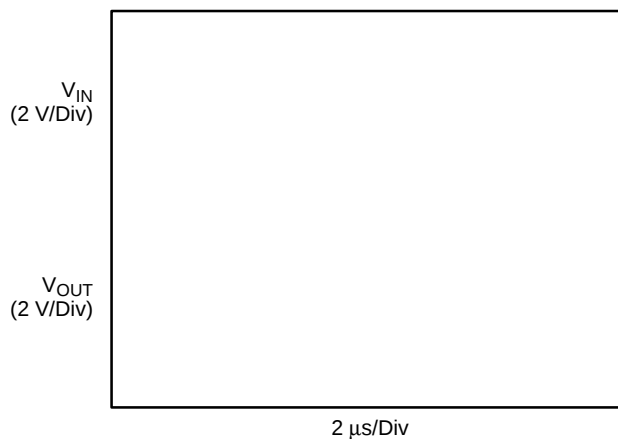
Graph 11. Pulse Response



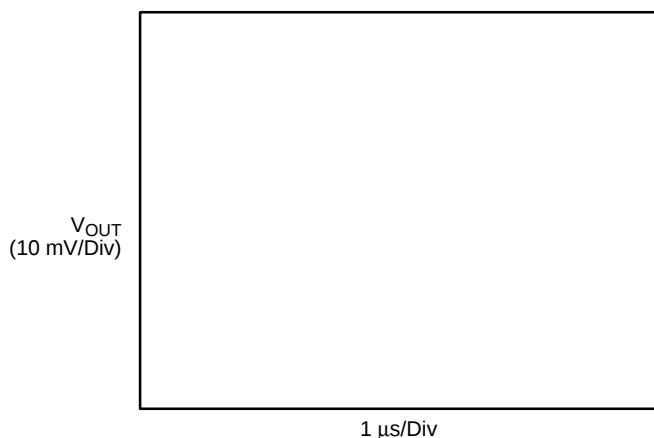
Graph 12. 1 LSB Digital Step Change



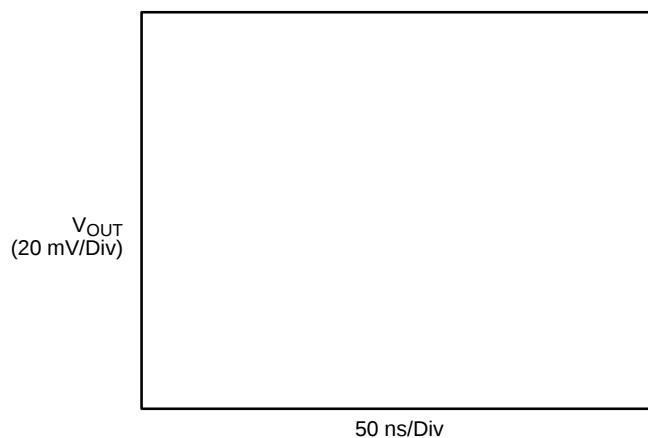
Graph 13. Settling Time



Graph 14. 128kHz Sawtooth Waveform Response



Graph 15. Clock Feedthrough



Graph 16. Digital Crosstalk

V_{OUT}
(5 dB/Div)



kHz

Graph 17. PSRR vs. Frequency

Gain
(5 dB/Div)

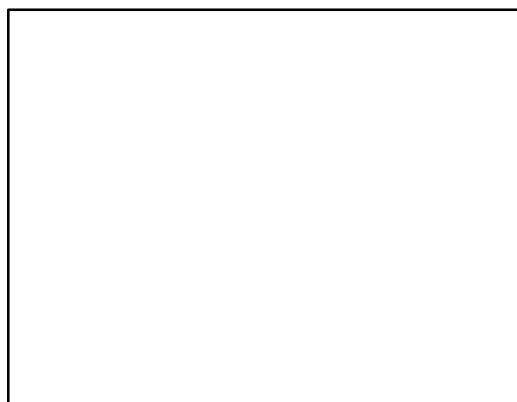
Phase
(20°/Div)



MHz

Graph 18. Gain and Phase vs. Frequency

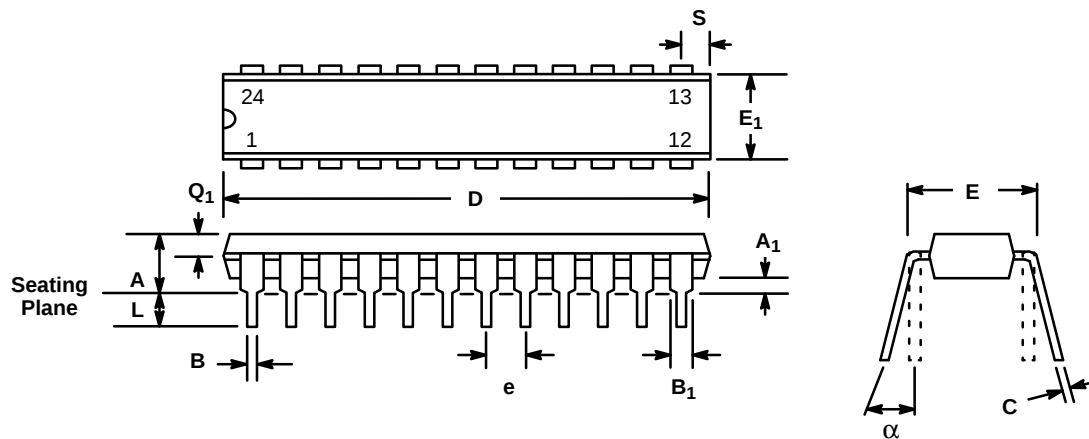
V_{OUT}
(20 mV/Div)



50 ns/Div

Graph 19. Digital Feedthrough

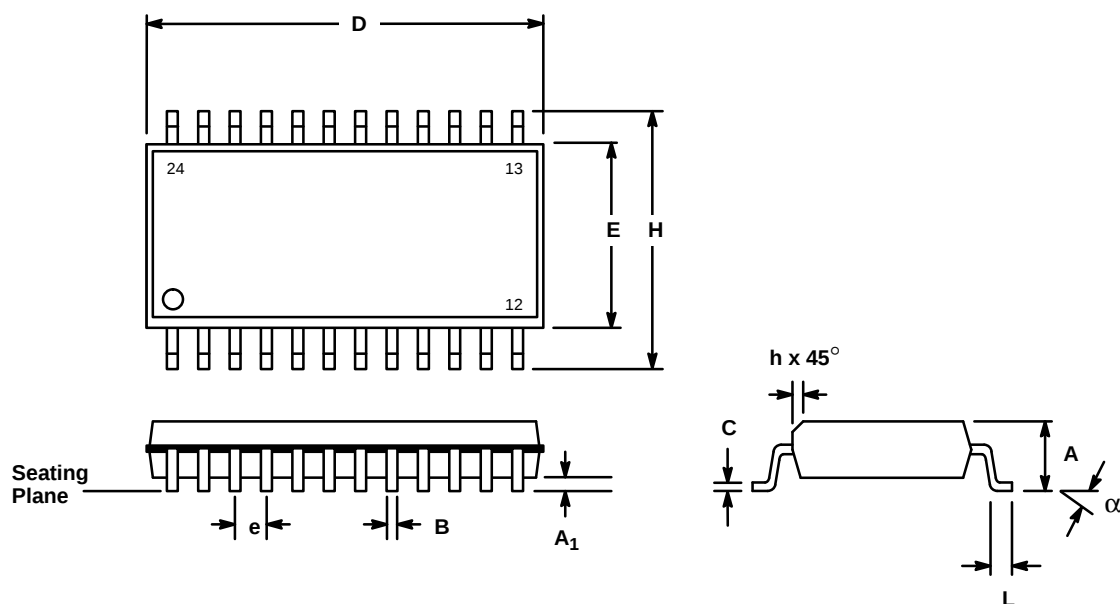
**24 LEAD PLASTIC DUAL-IN-LINE
(300 MIL PDIP)
NN24**



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	—	0.200	—	5.08
A ₁	0.015	—	0.38	—
B	0.014	0.023	0.356	0.584
B ₁ (1)	0.038	0.065	0.965	1.65
C	0.008	0.015	0.203	0.381
D	1.16	1.280	29.46	32.51
E	0.295	0.325	7.49	8.26
E ₁	0.220	0.310	5.59	7.87
e	0.100 BSC		2.54 BSC	
L	0.115	0.150	2.92	3.81
α	0°	15°	0°	15°
Q ₁	0.055	0.070	1.40	1.78
S	0.028	0.098	0.711	2.49

Note: (1) The minimum limit for dimensions B1 may be 0.023" (0.58 mm) for all four corner leads only.

24 LEAD SMALL OUTLINE
(300 MIL JEDEC SOIC)
S24



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.097	0.104	2.464	2.642
A1	0.0050	0.0115	0.127	0.292
B	0.014	0.019	0.356	0.483
C	0.0091	0.0125	0.231	0.318
D	0.602	0.612	15.29	15.54
E	0.292	0.299	7.42	7.59
e	0.050 BSC		1.27 BSC	
H	0.400	0.410	10.16	10.41
h	0.010	0.016	0.254	0.406
L	0.016	0.035	0.406	0.889
α	0°	8°	0°	8°

Notes

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Datasheet April 1995

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